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Microsemi FPGAs and cSoCs Available for Extreme Temperature Environments

Programmable Devices Operate at 150 Degrees Celsius to 200 Degrees Celsius

ALISO VIEJO, Calif., June 14, 2012 /PRNewswire/ -- **Microsemi Corporation** (Nasdaq: MSCC), a leading provider of semiconductor solutions differentiated by power, security, reliability and performance, today announced that its field programmable gate arrays (FPGAs) and SmartFusion® customizable system-on-chip (cSoC) solutions are now characterized at extreme operating temperatures ranging from 150 degrees Celsius to 200 degrees Celsius. The devices have already been deployed in down-hole drilling products, space systems, avionics equipment and other applications requiring high performance and the utmost reliability in extreme low and high temperature environments.

(Logo: <http://photos.prnewswire.com/prnh/20110909/MM66070LOGO>)

"Components that are capable of highly reliable operation in extreme hot and cold temperatures are essential for oil exploration applications, aerospace and defense equipment, and other products used in harsh operating environments," said Paul Ekas, vice president of marketing for Microsemi's SoC product group. "Our new extreme temperature solutions demonstrate our continued commitment to delivering consistently high quality solutions that address tough industry challenges."

The following Microsemi products are now available in extreme operating temperature ranges:

<i>Product</i>	<i>Technology</i>	<i>Characteristic</i>
SmartFusion® (A2F)	Mixed Signal (Flash)	Reprogrammable
Fusion (AFS)	Mixed Signal (Flash)	Reprogrammable
ProASIC®3 (A3P)	Flash	Reprogrammable
IGLOO (AGL)	Flash	Reprogrammable
ProASIC ^{PLUS} (APA)	Flash	Reprogrammable
SX-A	Antifuse	One-time-programmable
MX	Antifuse	One-time-programmable
ACT1, 2, 3	Antifuse	One-time-programmable

For additional information, please contact a local Microsemi sales representative or visit www.microsemi.com/soc/extremetemp.

About Microsemi

Microsemi Corporation (Nasdaq: MSCC) offers a comprehensive portfolio of semiconductor and system solutions for communications, defense and security, aerospace, as well as industrial and medical markets. Products include mixed-signal integrated circuits, SoCs and ASICs; programmable logic solutions; power management products; timing and voice processing devices; RF solutions; discrete components; and Power-over-Ethernet ICs and midspans. Microsemi is headquartered in Aliso Viejo, Calif., and has approximately 3,000 employees globally. Learn more at www.microsemi.com.

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"Safe Harbor" Statement under the Private Securities Litigation Reform Act of 1995: Any statements set forth in this news release that are not entirely historical and factual in nature, including without limitation statements related to its new extreme temperature products, and its potential effects on future business, are forward-looking statements. These forward-looking statements are based on our current expectations and are inherently subject to risks and uncertainties that could cause actual results to differ materially from those expressed in the forward-looking statements. The potential risks and uncertainties include, but are not limited to, such factors as rapidly changing technology and product obsolescence, potential cost increases, variations in customer order preferences, weakness or competitive pricing environment of the marketplace, uncertain demand for and acceptance of the company's products, adverse circumstances in any of our end markets, results of in-process or planned development or marketing and promotional campaigns, difficulties foreseeing future demand, potential non-realization of expected orders or non-realization of backlog, product returns, product liability, and other potential unexpected business and economic conditions or adverse changes in current or expected industry conditions, difficulties and costs of protecting patents and other proprietary rights, inventory obsolescence and difficulties regarding customer qualification of products. In addition to these factors and any other factors mentioned elsewhere in this news release, the reader should refer as well to the factors, uncertainties or risks identified in the company's most recent Form 10-K and all subsequent Form 10-Q reports filed by Microsemi with the SEC. Additional risk factors may be identified from time to time in Microsemi's future filings. The forward-looking statements included in this release speak only as of the date hereof, and Microsemi does not undertake any obligation

to update these forward-looking statements to reflect subsequent events or circumstances.

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